

FS10ASJ-06F

High-Speed Switching Use
Nch Power MOS FET

REJ03G0241-0100

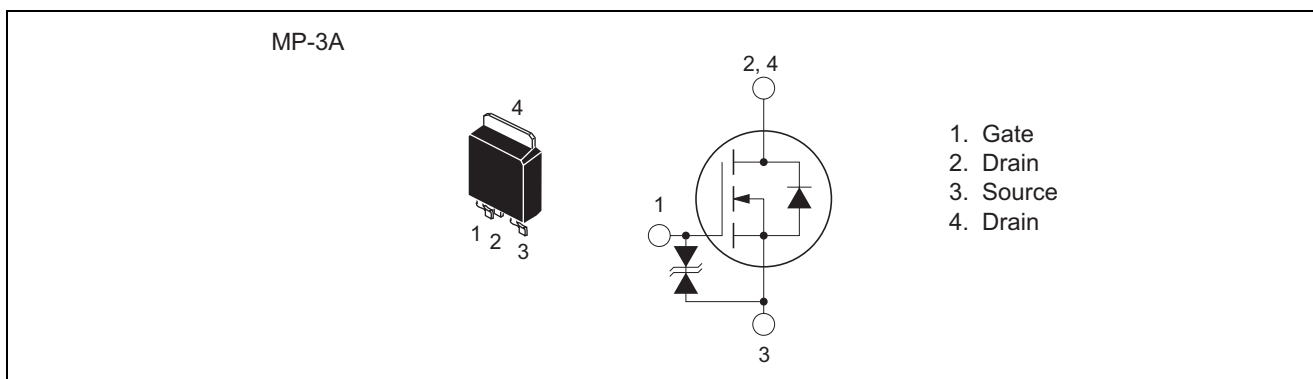
Rev.1.00

Aug.20.2004

Features

- Drive voltage : 4 V
- V_{DSS} : 60 V
- $r_{DS(ON)(max)}$: 70 m Ω
- I_D : 10 A
- Recovery Time of the Integrated Fast Recovery Diode (TYP.) : 30 ns

Outline



Applications

Motor control, lamp control, solenoid control, DC-DC converters, etc.

Maximum Ratings

(Tc = 25°C)

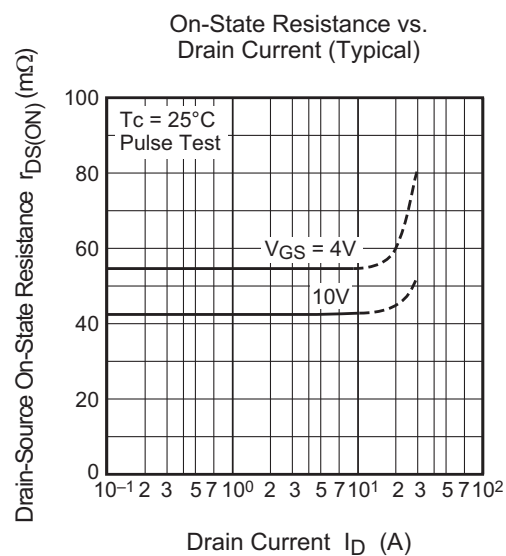
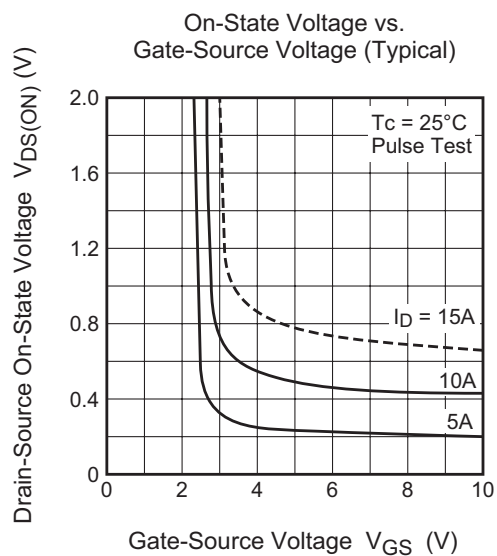
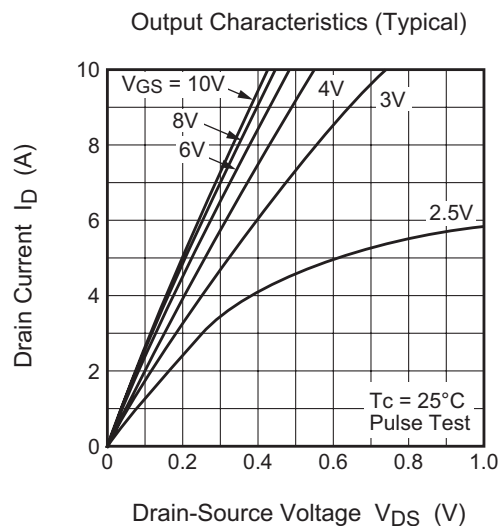
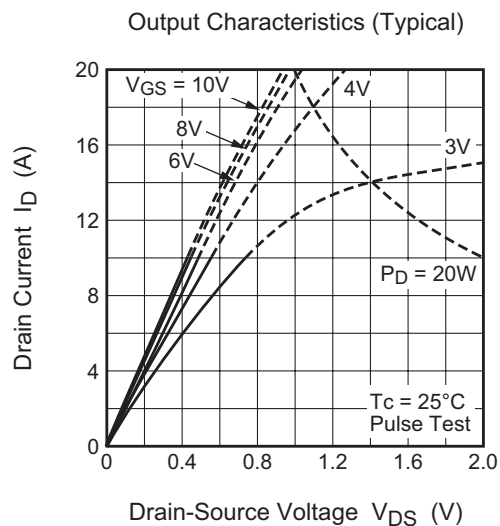
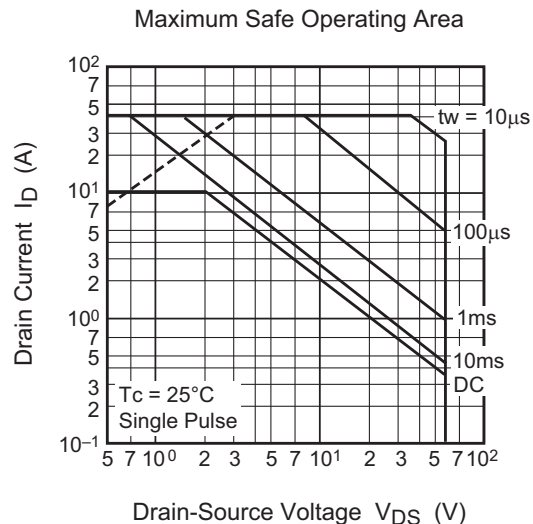
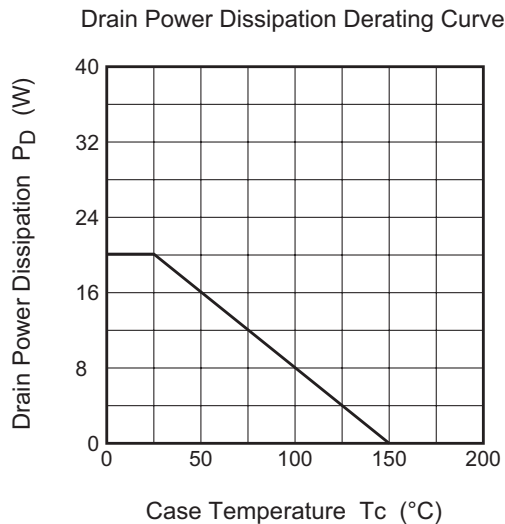
Parameter	Symbol	Ratings	Unit	Conditions
Drain-source voltage	V_{DSS}	60	V	$V_{GS} = 0$ V
Gate-source voltage	V_{GSS}	± 20	V	$V_{DS} = 0$ V
Drain current	I_D	10	A	
Drain current (Pulsed)	I_{DM}	40	A	
Avalanche current (Pulsed)	I_{DA}	10	A	$L = 50$ μ H
Source current	I_S	10	A	
Source current (Pulsed)	I_{SM}	40	A	
Maximum power dissipation	P_D	20	W	
Channel temperature	Tch	- 55 to +150	°C	
Storage temperature	Tstg	- 55 to +150	°C	
Mass	—	0.32	g	Typical value

Electrical Characteristics

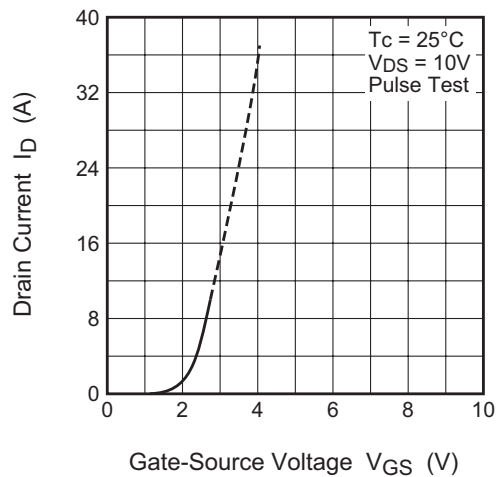
(Tch = 25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test conditions
Drain-source breakdown voltage	$V_{(BR)DSS}$	60	—	—	V	$I_D = 1 \text{ mA}$, $V_{GS} = 0 \text{ V}$
Gate-source breakdown voltage	$V_{(BR)GSS}$	± 20	—	—	V	$I_G = \pm 100 \text{ }\mu\text{A}$, $V_{DS} = 0 \text{ V}$
Drain-source leakage current	I_{DSS}	—	—	100	μA	$V_{DS} = 60 \text{ V}$, $V_{GS} = 0 \text{ V}$
Gate-source leakage current	I_{GSS}	—	—	± 10	μA	$V_{GS} = \pm 20 \text{ V}$, $V_{DS} = 0 \text{ V}$
Gate-source threshold voltage	$V_{GS(th)}$	1.0	1.5	2.0	V	$I_D = 1 \text{ mA}$, $V_{DS} = 10 \text{ V}$
Drain-source on-state resistance	$r_{DS(ON)}$	—	53	70	$\text{m}\Omega$	$I_D = 5 \text{ A}$, $V_{GS} = 10 \text{ V}$
Drain-source on-state resistance	$r_{DS(ON)}$	—	66	86	$\text{m}\Omega$	$I_D = 5 \text{ A}$, $V_{GS} = 4 \text{ V}$
Drain-source on-state voltage	$V_{DS(ON)}$	—	0.27	0.35	V	$I_D = 5 \text{ A}$, $V_{GS} = 10 \text{ V}$
Forward transfer admittance	$ y_{fs} $	—	13	—	S	$I_D = 5 \text{ A}$, $V_{DS} = 10 \text{ V}$
Input capacitance	C_{iss}	—	750	—	pF	$V_{DS} = 10 \text{ V}$, $V_{GS} = 0 \text{ V}$, $f = 1 \text{ MHz}$
Output capacitance	C_{oss}	—	130	—	pF	
Reverse transfer capacitance	C_{rss}	—	80	—	pF	
Turn-on delay time	$t_{d(on)}$	—	7	—	ns	$V_{DD} = 30 \text{ V}$, $I_D = 5 \text{ A}$, $V_{GS} = 10 \text{ V}$, $R_{GEN} = R_{GS} = 50 \text{ }\Omega$
Rise time	t_r	—	18	—	ns	
Turn-off delay time	$t_{d(off)}$	—	70	—	ns	
Fall time	t_f	—	35	—	ns	
Source-drain voltage	V_{SD}	—	1.0	1.5	V	$I_S = 5 \text{ A}$, $V_{GS} = 0 \text{ V}$
Thermal resistance	$R_{th(ch-c)}$	—	—	6.25	$^{\circ}\text{C/W}$	Channel to case
Reverse recovery time	t_{rr}	—	30	—	ns	$I_S = 10 \text{ A}$, $\text{dis}/\text{dt} = -100 \text{ A}/\mu\text{s}$

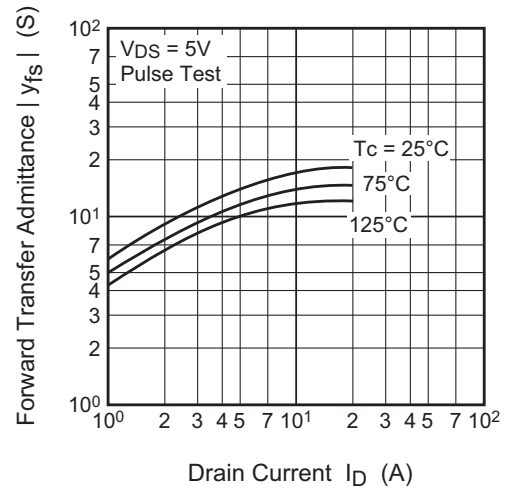
Performance Curves



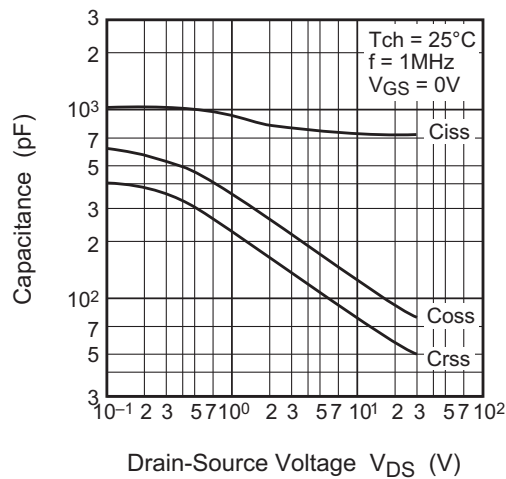
Transfer Characteristics (Typical)



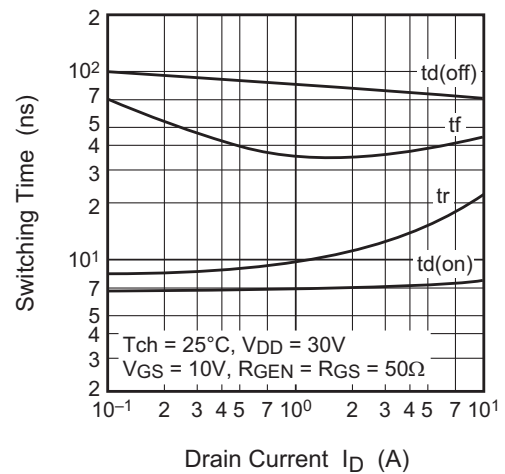
Forward Transfer Admittance vs. Drain Current (Typical)



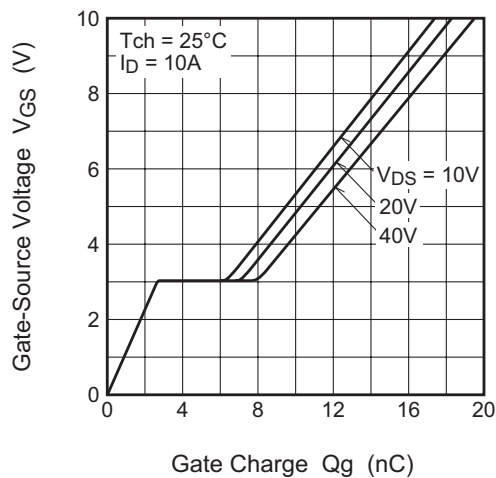
Capacitance vs. Drain-Source Voltage (Typical)



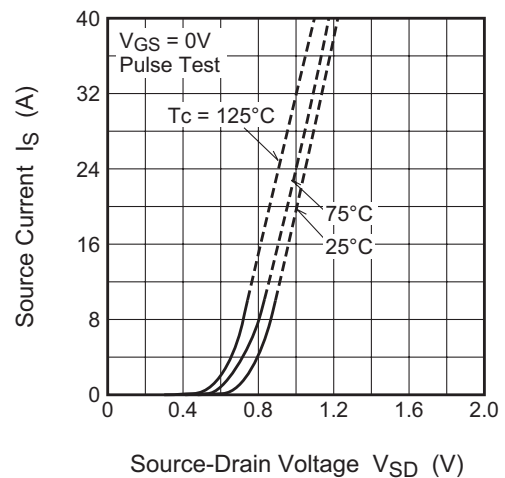
Switching Characteristics (Typical)

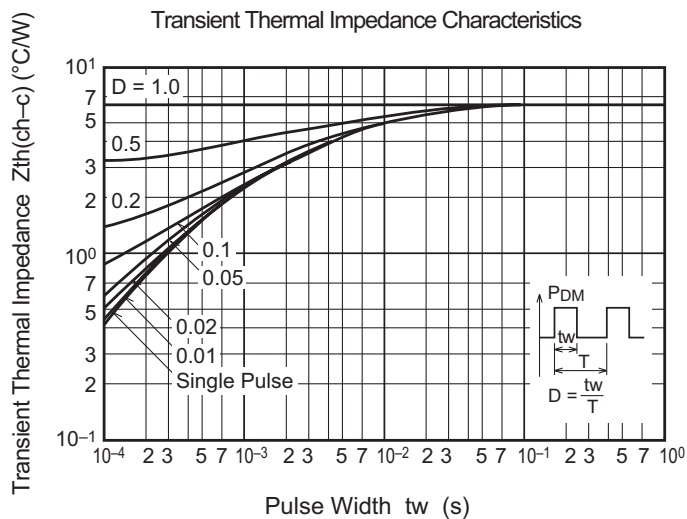
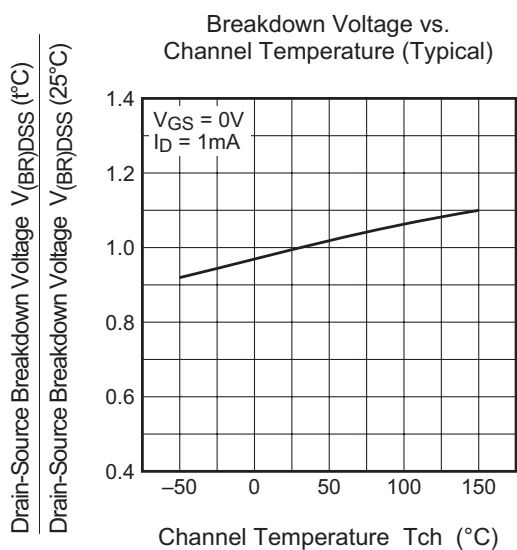
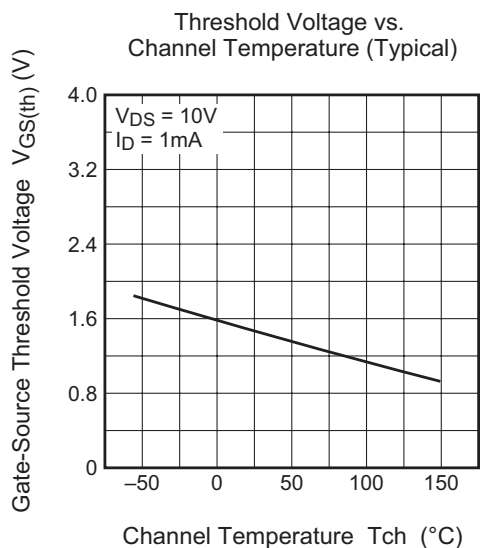
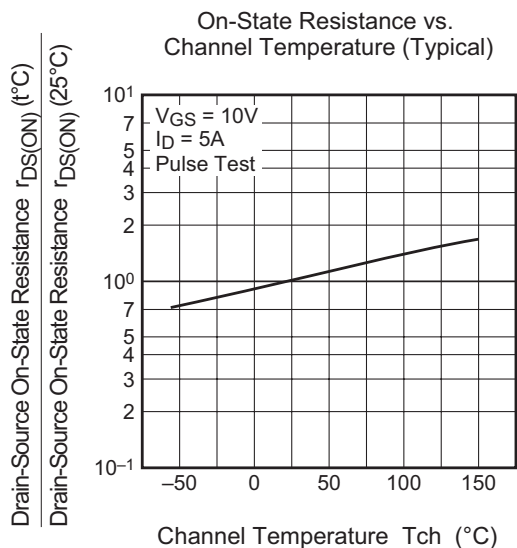


Gate-Source Voltage vs. Gate Charge (Typical)

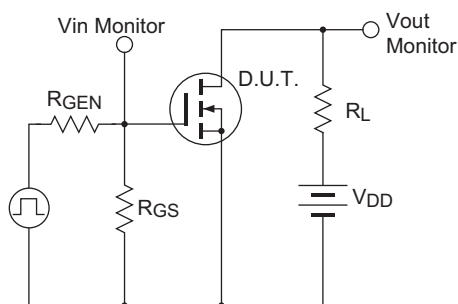


Source-Drain Diode Forward Characteristics (Typical)

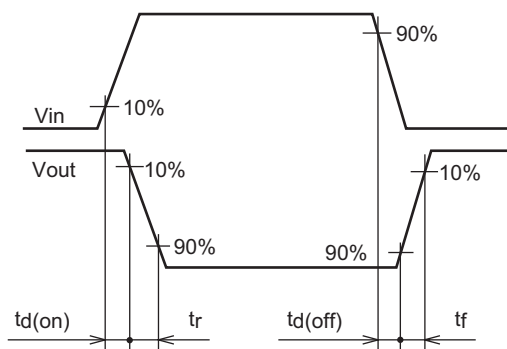




Switching Time Measurement Circuit



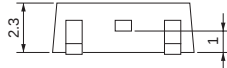
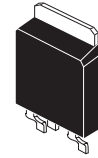
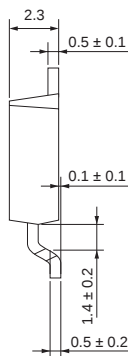
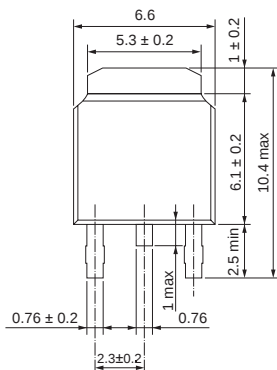
Switching Waveform



Package Dimensions

MP-3A

EIAJ Package Code	JEDEC Code	Mass (g) (reference value)	Lead Material
—	—	0.32	Cu alloy



Note 1) The dimensional figures indicate representative values unless otherwise the tolerance is specified.

Symbol	Dimension in Millimeters		
	Min	Typ	Max
A	—	—	—
A ₁	—	—	—
A ₂	—	—	—
b	—	—	—
D	—	—	—
E	—	—	—
e	—	—	—
x	—	—	—
y	—	—	—
y ₁	—	—	—
ZD	—	—	—
ZE	—	—	—

Order Code

Lead form	Standard packing	Quantity	Standard order code	Standard order code example
Surface-mounted type	Taping	3000	Type name – T +Direction (1 or 2) +3	FS10ASJ-06F-T13
Surface-mounted type	Plastic Magazine (Tube)	75	Type name	FS10ASJ-06F

Note : Please confirm the specification about the shipping in detail.

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